TechniFlex LCL1000F/423M U8F

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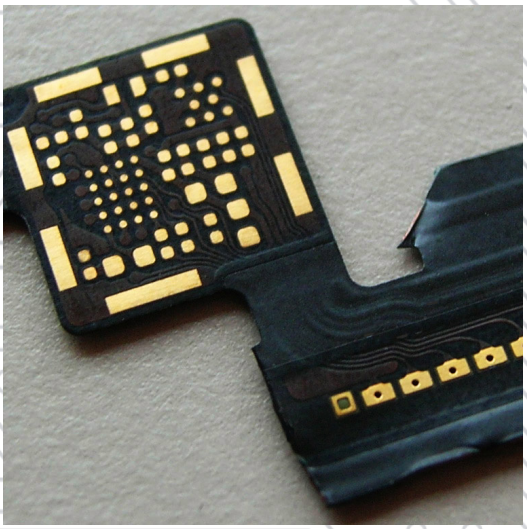
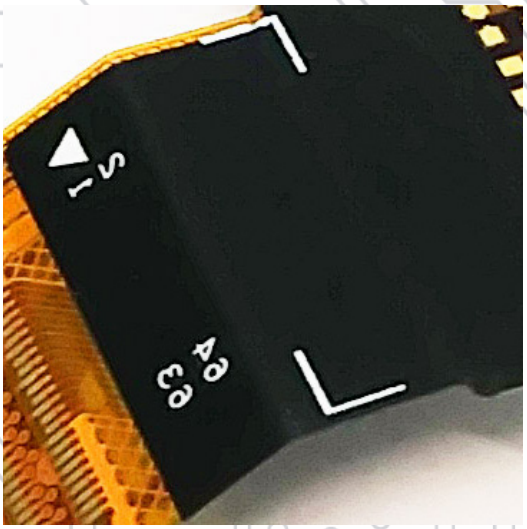
Halogen Free, LED/UV Direct Photoimageable, Black Matte, Flexible Solder Mask

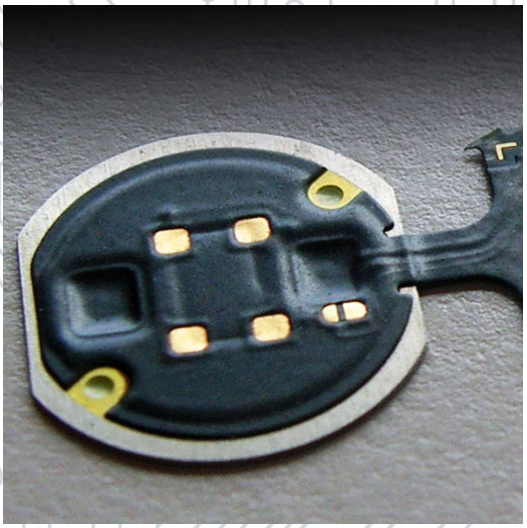


TechniFlex LCL 1000F/423M U8F Direct Imaging is a liquid photo-definable halogen-free highly flexible black matte solder mask, specially designed for low exposure energy with recently available high output direct imaging systems. It is composed of next generation resin and multiple photoinitiator components, capable of being utilized with standard exposing and UV/LED/ Multiple laser direct imaging systems. This DI product exhibits very high flexibility and elasticity and is active silicone free. It is resistant to multiple soldering operations and is capable of lead-free soldering/hot bar processing.



Features

- Extremely high flexibility and elasticity before and after primary baking
- High heat resistance
- Low exposure energy
- Tack free surface after drying
- Active silicone free
- REACH SVHC Compliant



Benefits

- PFB exhibits reduced warpage after final cure
- Withstands multiple soldering operations
- Increased productivity with lower exposure times
- Stackable after drying prior to exposure
- Increased adhesion to stiffener/coverlay materials

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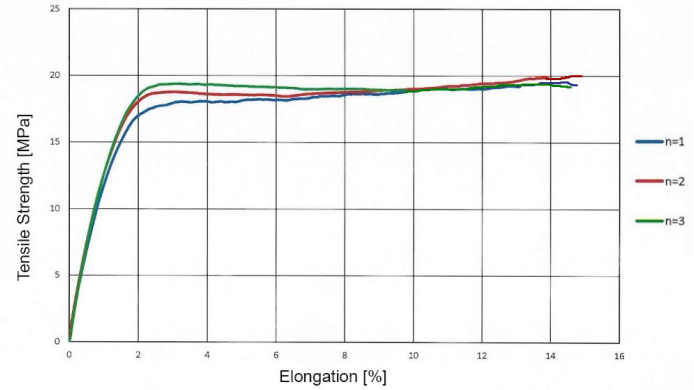
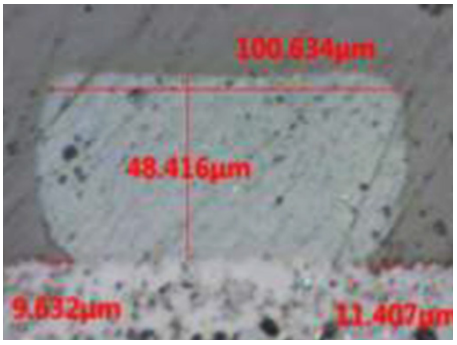
Performance Properties:

- Extremely high flexibility and elasticity before and after baking
- High heat resistance to multiple soldering operations, capable of lead-free soldering/hot bar processing
- High 365nm spectra absorption along with 405nm
- Low exposure energy with minimized undercut
- Resolution capability below 3 mils for ultra-fine pitch dams
- Tack-free surface for stackable processing
- Active Silicone Free formulation
- Excellent black cosmetic appearance with minimal imaging circuit diagrams
- Can use either standard exposure equipment or UV/LED/multiple laser direct imaging systems
- Meets or exceeds IPC SM 840E, Bellcore TR-NWT-000078, and MIL P55110D specifications
- UL 94 V-0/VTM-0 certified product/File #E83246, meets minimum 94 VTM-0 specifications with specific parameters (PI grade, PI thickness, and solder mask thickness) under UL certifications. (see UL certification note)
- Complies with NASA outgassing specification (MICRO VCM TEST/ASTM E-595-93)
- Halogen, Sb, Be, and Phthalate Free - RoHS compliant
- Superior resistance to all plated surface finishing processes including ENIG, ENEPIG, Tin-Lead, Nickel, and Tin
- Resistant to downstream processing chemicals including no-clean fluxes, cleaners, solvents, etc.



High flexibility and elasticity



Fine solder dam features
exhibit minimized undercut

Superior resistance to plated surface finishes
and downstream processing chemicals

High heat resistance
340°C for 5 sec dipping x 3 times

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